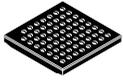


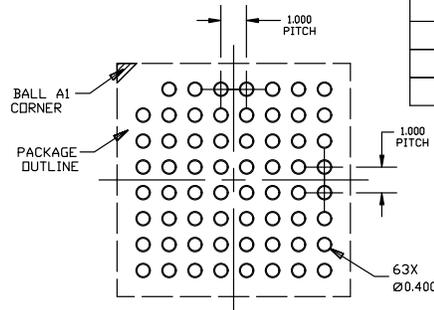
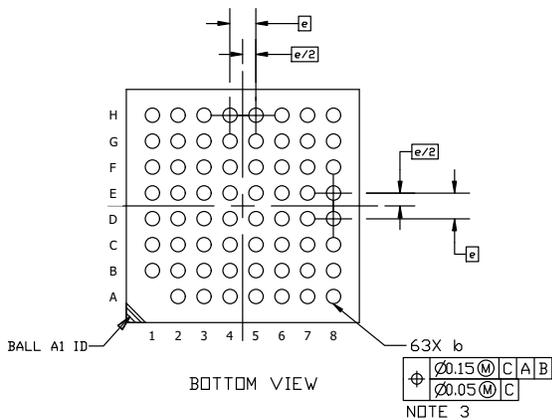
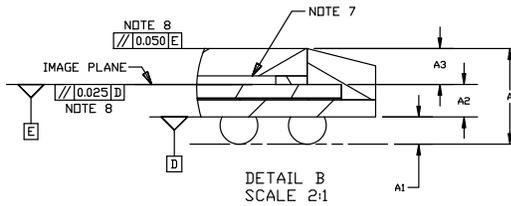
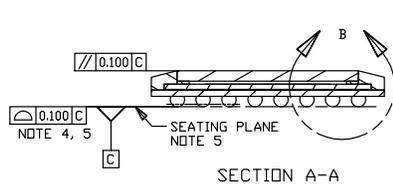
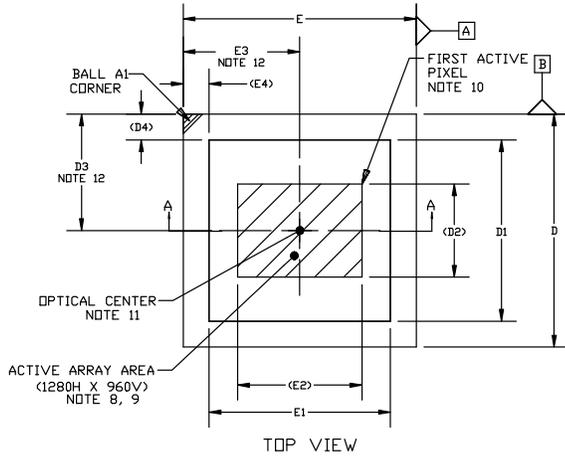
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 1:1

**IBGA63 9x9**  
**CASE 503AZ**  
**ISSUE C**

DATE 06 JAN 2023

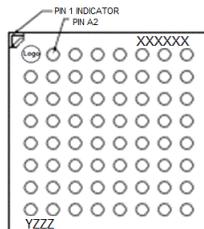


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS (mm).
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52; AR COATING R(1% 420-850nm) EACH SIDE.
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.125 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS ±0.5°.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. PACKAGE CENTER (X, Y) = (0.000, 0.000).
12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.000, 0.000).

| DIM | MILLIMETERS |       |       |
|-----|-------------|-------|-------|
|     | MIN.        | NOM.  | MAX.  |
| A   | ~           | ~     | 1.550 |
| A1  | 0.350       | 0.400 | 0.450 |
| A2  | 0.425       | 0.475 | 0.525 |
| A3  | 0.475       | 0.525 | 0.575 |
| b   | 0.450       | 0.500 | 0.550 |
| D   | 8.925       | 9.000 | 9.075 |
| D1  | 6.900       | 7.000 | 7.100 |
| D2  | 3.600 REF   |       |       |
| D3  | 4.425       | 4.500 | 4.575 |
| D4  | 1.002 REF   |       |       |
| E   | 8.925       | 9.000 | 9.075 |
| E1  | 6.900       | 7.000 | 7.100 |
| E2  | 4.800 REF   |       |       |
| E3  | 4.425       | 4.500 | 4.575 |
| E4  | 0.999 REF   |       |       |
| e   | 1.000 BSC   |       |       |

**GENERIC MARKING DIAGRAM\***



XXXX = Specific Device Code  
Y = Year  
ZZZ = Lot Traceability

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present. Some products may not follow the Generic Marking.

|                         |                    |  |
|-------------------------|--------------------|--|
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| <b>DESCRIPTION:</b>     | <b>IBGA63 9x9</b>  | <b>PAGE 1 OF 1</b>   |

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